

C3D20060D

Silicon Carbide Schottky Diode

Z-REC[®] RECTIFIER

| | | |
|-------------------------------|---|---------|
| V_{RRM} | = | 600 V |
| $I_F (T_c=135^\circ\text{C})$ | = | 26 A** |
| Q_c | = | 48 nC** |

Features

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

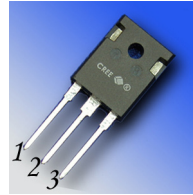
Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies (SMPS)
- Boost diodes in PFC or DC/DC stages
- Free Wheeling Diodes in Inverter stages
- AC/DC converters

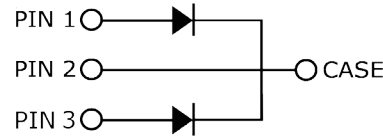
Package



TO-247-3



AEC-Q101 Qualified



| Part Number | Package | Marking |
|-------------|----------|----------|
| C3D20060D | TO-247-3 | C3D20060 |

Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Value | Unit | Test Conditions | Note |
|----------------|---|---------------------------|------------------|---|--------|
| V_{RRM} | Repetitive Peak Reverse Voltage | 600 | V | | |
| V_{RSM} | Surge Peak Reverse Voltage | 600 | V | | |
| V_{DC} | DC Blocking Voltage | 600 | V | | |
| I_F | Continuous Forward Current (Per Leg/Device) | 27.5/55 13/26 10/20 | A | $T_c=25^\circ\text{C}$ $T_c=135^\circ\text{C}$ $T_c=149^\circ\text{C}$ | Fig. 3 |
| I_{FRM} | Repetitive Peak Forward Surge Current | 46* 31* | A | $T_c=25^\circ\text{C}, t_p = 10 \text{ ms}, \text{Half Sine Wave}$ $T_c=110^\circ\text{C}, t_p = 10 \text{ ms}, \text{Half Sine Wave}$ | |
| I_{FSM} | Non-Repetitive Peak Forward Surge Current | 90* 71* | A | $T_c=25^\circ\text{C}, t_p = 10 \text{ ms}, \text{Half Sine Wave}$ $T_c=110^\circ\text{C}, t_p = 10 \text{ ms}, \text{Half Sine Wave}$ | Fig. 8 |
| I_{FSM} | Non-Repetitive Peak Forward Surge Current | 860* 680* | A | $T_c=25^\circ\text{C}, t_p = 10 \mu\text{s}, \text{Pulse}$ $T_c=110^\circ\text{C}, t_p = 10 \mu\text{s}, \text{Pulse}$ | Fig. 8 |
| P_{tot} | Power Dissipation (Per Leg/Device) | 136.5 59 | W | $T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$ | Fig. 4 |
| dV/dt | Diode dV/dt ruggedness | 200 | V/ns | $V_R=0-650\text{V}$ | |
| T_J, T_{stg} | Operating Junction and Storage Temperature | -55 to +175 | $^\circ\text{C}$ | | |
| | TO-247 Mounting Torque | 1 8.8 | Nm lbf-in | M3 Screw 6-32 Screw | |

* Per Leg, ** Per Device

Electrical Characteristics (Per Leg)

| Symbol | Parameter | Typ. | Max. | Unit | Test Conditions | Note |
|--------|---------------------------|-------------------|------------|---------------|--|--------|
| V_F | Forward Voltage | 1.5 2.0 | 1.8 2.4 | V | $I_F = 10\text{ A}$ $T_J = 25^\circ\text{C}$ $I_F = 10\text{ A}$ $T_J = 175^\circ\text{C}$ | Fig. 1 |
| I_R | Reverse Current | 10 20 | 50 200 | μA | $V_R = 600\text{ V}$ $T_J = 25^\circ\text{C}$ $V_R = 600\text{ V}$ $T_J = 175^\circ\text{C}$ | Fig. 2 |
| Q_C | Total Capacitive Charge | 24 | | nC | $V_R = 400\text{ V}$, $I_F = 10\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$ | Fig. 5 |
| C | Total Capacitance | 460.5 44 40 | | pF | $V_R = 0\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ $V_R = 200\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ $V_R = 400\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ | Fig. 6 |
| E_C | Capacitance Stored Energy | 3.6 | | μJ | $V_R = 400\text{ V}$ | Fig. 7 |

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

| Symbol | Parameter | Typ. | Unit | Note |
|-----------------|--|----------------|---------------------------|--------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case | 1.3** 0.65* | $^\circ\text{C}/\text{W}$ | Fig. 9 |

** Per Leg, * Both Legs

Typical Performance (Per Leg)

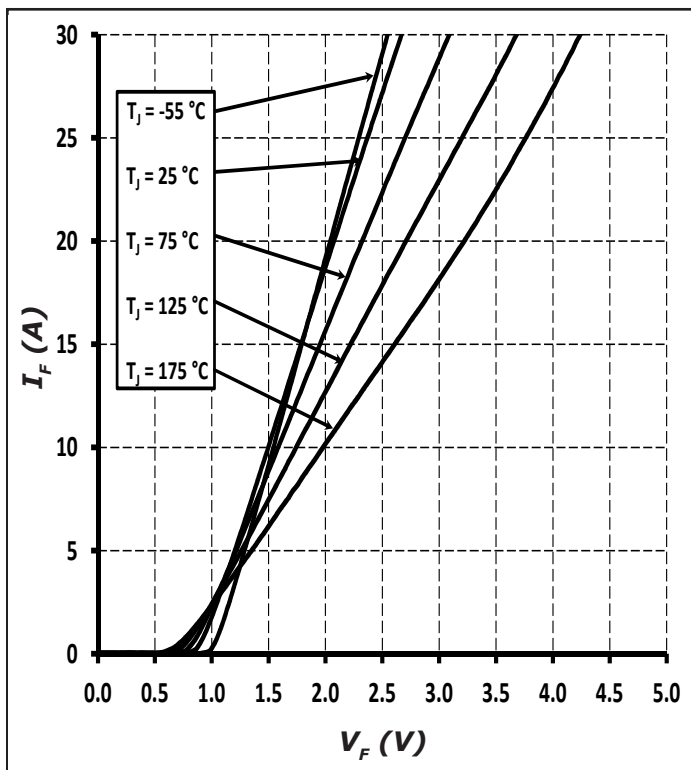


Figure 1. Forward Characteristics

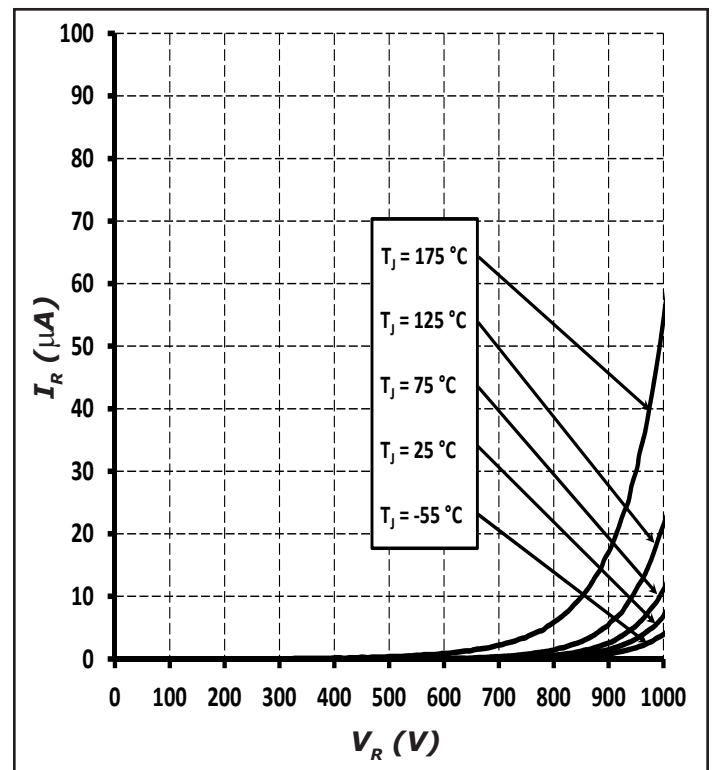


Figure 2. Reverse Characteristics

Typical Performance (Per Leg)

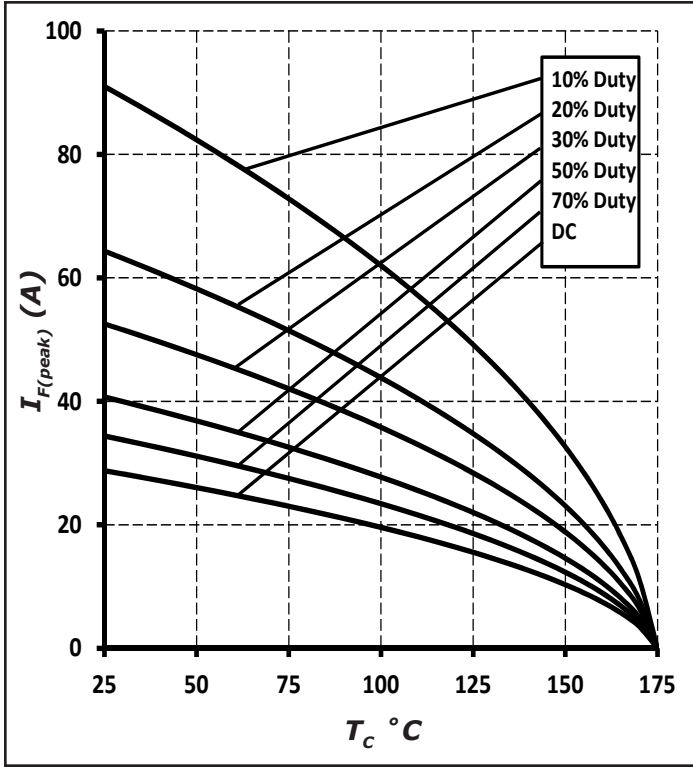


Figure 3. Current Derating

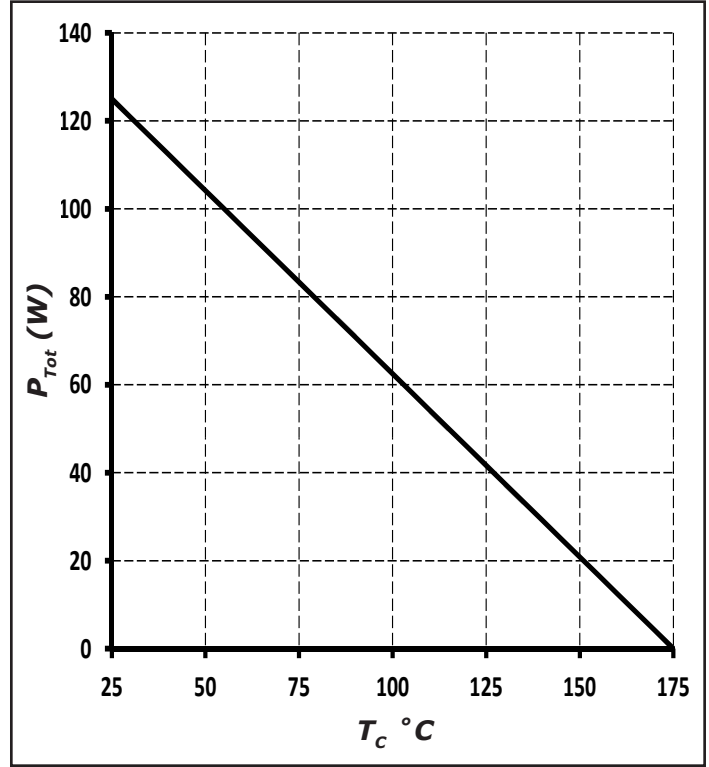


Figure 4. Power Derating

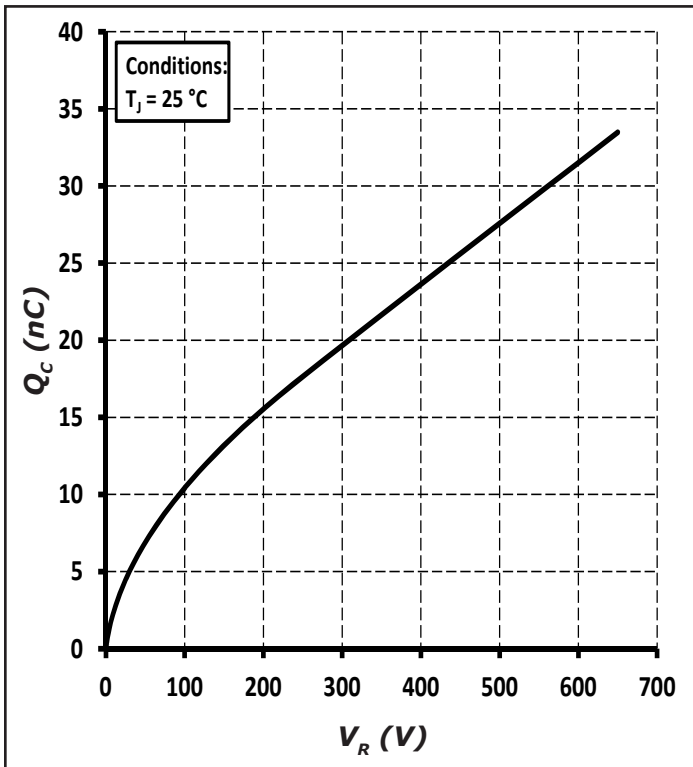


Figure 5. Total Capacitance Charge vs. Reverse Voltage

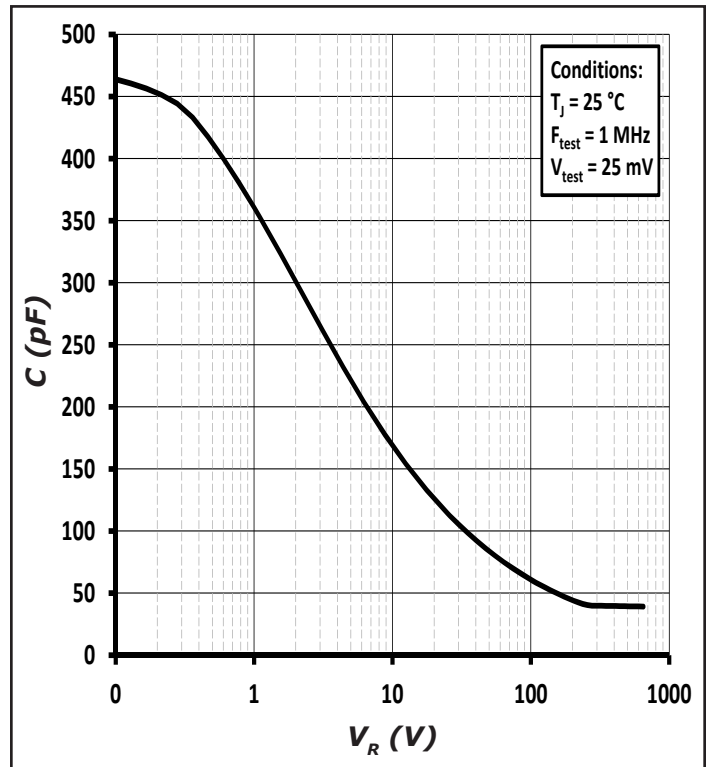


Figure 6. Capacitance vs. Reverse Voltage

Typical Performance

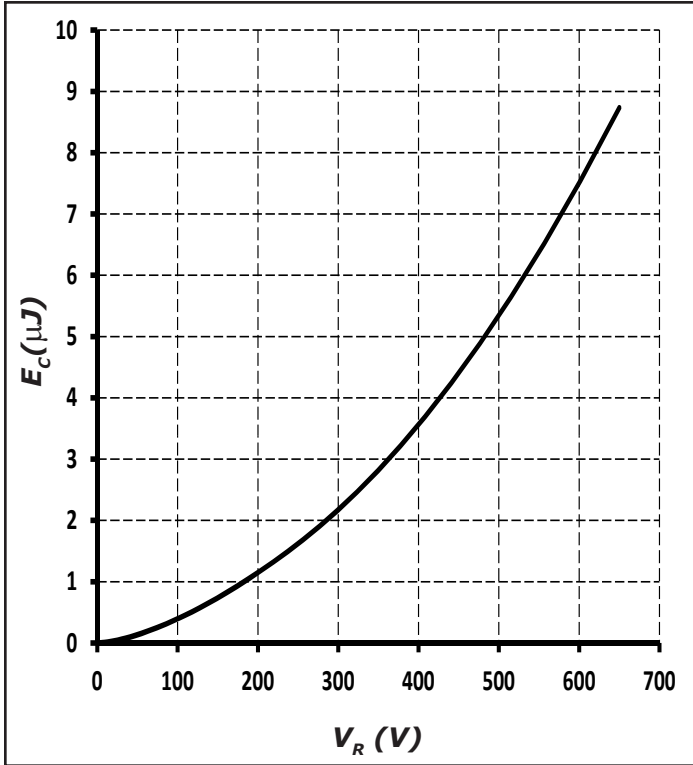


Figure 7. Capacitance Stored Energy

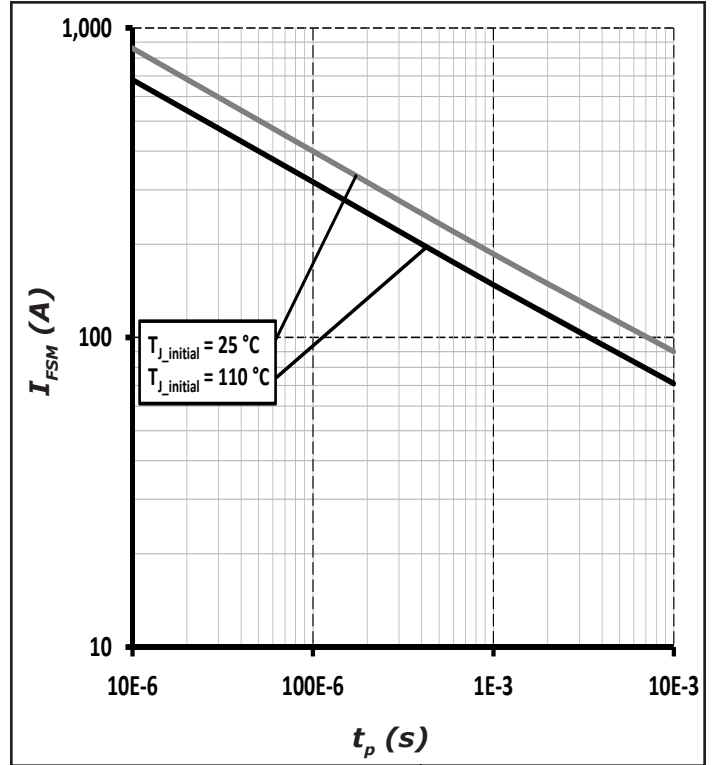


Figure 8. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)

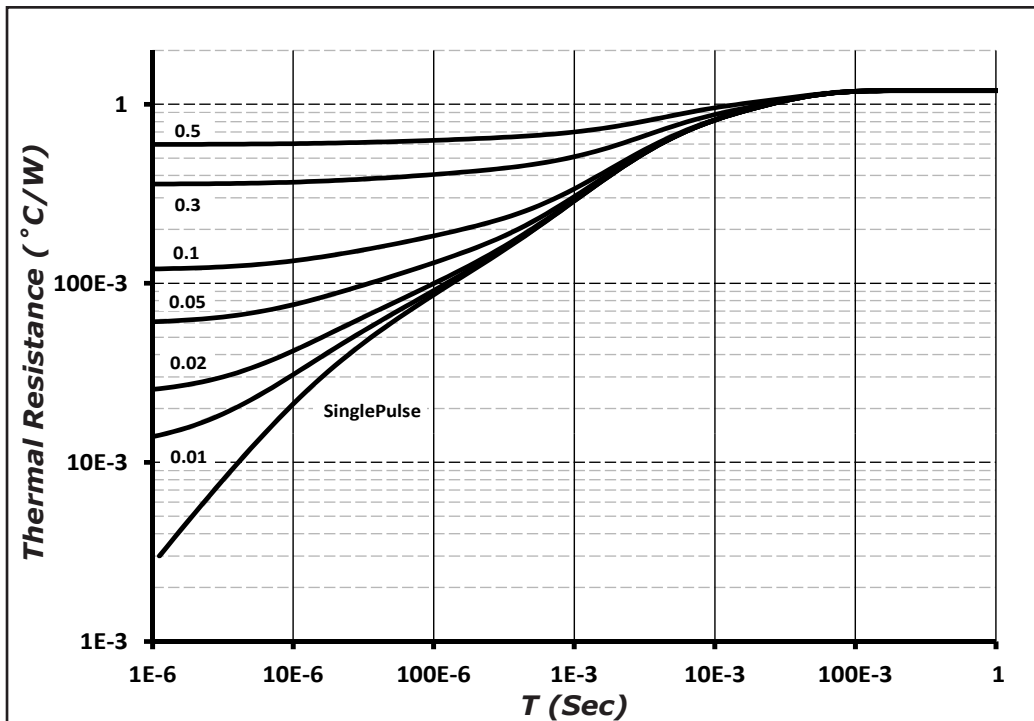
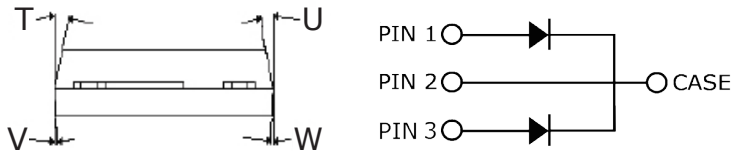
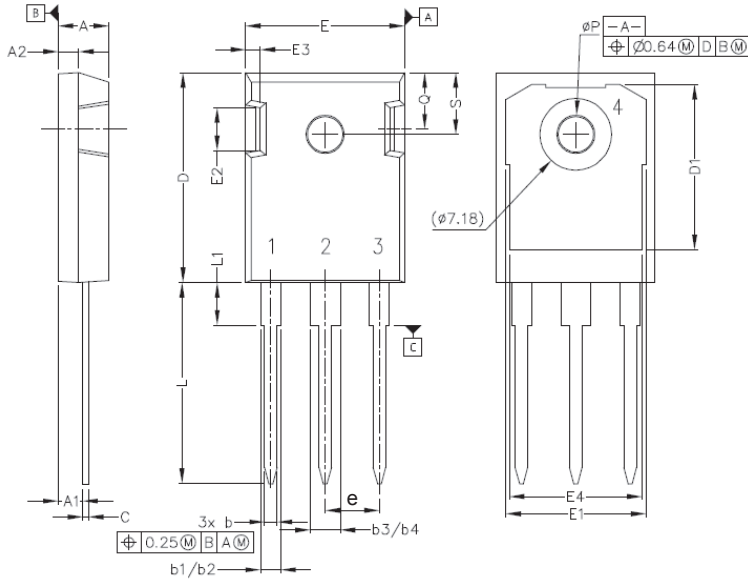


Figure 9. Transient Thermal Impedance

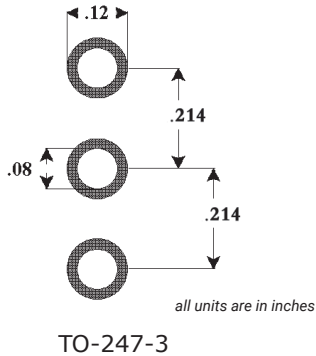
Package Dimensions

Package TO-247-3



| POS | Inches | | Millimeters | |
|----------|----------|------|-------------|-------|
| | Min | Max | Min | Max |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .090 | .100 | 2.29 | 2.54 |
| A2 | .075 | .085 | 1.91 | 2.16 |
| b | .042 | .052 | 1.07 | 1.33 |
| b1 | .075 | .095 | 1.91 | 2.41 |
| b2 | .075 | .085 | 1.91 | 2.16 |
| b3 | .113 | .133 | 2.87 | 3.38 |
| b4 | .113 | .123 | 2.87 | 3.13 |
| c | .022 | .027 | 0.55 | 0.68 |
| D | .819 | .831 | 20.80 | 21.10 |
| D1 | .640 | .695 | 16.25 | 17.65 |
| D2 | .037 | .049 | 0.95 | 1.25 |
| E | .620 | .635 | 15.75 | 16.13 |
| E1 | .516 | .557 | 13.10 | 14.15 |
| E2 | .145 | .201 | 3.68 | 5.10 |
| E3 | .039 | .075 | 1.00 | 1.90 |
| E4 | .487 | .529 | 12.38 | 13.43 |
| e | .214 BSC | | 5.44 BSC | |
| N | 3 | | 3 | |
| L | .780 | .800 | 19.81 | 20.32 |
| L1 | .161 | .173 | 4.10 | 4.40 |
| ϕP | .138 | .144 | 3.51 | 3.65 |
| Q | .216 | .236 | 5.49 | 6.00 |
| S | .238 | .248 | 6.04 | 6.30 |
| T | 9° | 11° | 9° | 11° |
| U | 9° | 11° | 9° | 11° |
| V | 2° | 8° | 2° | 8° |
| W | 2° | 8° | 2° | 8° |

Recommended Solder Pad Layout



| Part Number | Package | Marking |
|-------------|----------|----------|
| C3D20060D | TO-247-3 | C3D20060 |

Note: Recommended soldering profiles can be found in the applications note here: http://www.wolfspeed.com/power_app_notes/soldering



Diode Model (Per Leg)



$$V_{fT} = V_T + I_f * R_T$$

$$V_T = 0.94 + (T_J * -1.3 * 10^{-3})$$

$$R_T = 0.044 + (T_J * 4.4 * 10^{-4})$$

Note: T_J = Diode Junction Temperature In Degrees Celsius, valid from 25°C to 175°C

Notes

- **RoHS Compliance**

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Ecology section of our website at <http://www.wolfspeed.com/Power/Tools-and-Support/Product-Ecology>.

- **REACH Compliance**

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

Related Links

- Cree SiC Schottky diode portfolio: <http://www.wolfspeed.com/SiCSchottkydiodes>
- Schottky diode Spice models: <http://www.wolfspeed.com/Schottky-diode-model-request>
- SiC MOSFET and diode reference designs: <http://www.wolfspeed.com/Power-reference-designs>